

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	12209	((438/353) or (438/359) or (438/400) or (438/421) or (438/422) or (438/424) or (438/437) or (438/453) or (438/597) or (438/598) or (438/619) or (438/637) or (438/638) or (438/642) or (438/643) or (438/652) or (438/653) or (438/667) or (438/668) or (438/672) or (438/675)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/07 21:23
L2	226429	(wafer\$1 and substrate\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:24
L3	2280786	(dielectric or insulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:25
L4	3287877	via\$1 or via\$1hole\$1 or hole\$1via\$1 or contact\$1hole\$1 or hole\$1contact\$1 or (via adj hole\$1) or (contact adj hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:27
L5	68199	2 and 3 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:27
L6	3393	1 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:27
L7	1212815	isolat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:28

EAST Search History

L8	1695463	semiconductor\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:28
L9	210206	7 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:28
L10	1493	6 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:29
L11	364	(438/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/07 21:37
L12	275	(438/620).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/07 21:37
L13	1782	(438/424).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/07 21:37
S1	10017	((438/353) or (438/359) or (438/400) or (438/421) or (438/422) or (438/424) or (438/437) or (438/453) or (438/597) or (438/598) or (438/619) or (438/637) or (438/638) or (438/642) or (438/643) or (438/652) or (438/653) or (438/667) or (438/668) or (438/672) or (438/675)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 15:50
S2	9	("4688069") or ("4733287") or ("4939567") or ("4949151") or ("5644157") or ("5760452") or ("6051868") or ("6472723") or ("6515334")).PN.	USPAT	OR	OFF	2004/11/28 20:49

EAST Search History

S3	847	S1 and (((first and second) near2 (dielectric or insulat\$3)) same (via\$1 or viahole\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 20:51
S4	397	S3 and wafer\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 20:52
S5	129	S4 and (isolat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 21:17
S6	25	("3614541" "4954458" "5128831" "5199165" "5202754" "5229647" "5270261" "5322816" "5401672" "5406120" "5419806" "5424245" "5432999" "5481133" "5502667" "5510655" "5528080" "5585675" "5600541" "5616517" "5621616" "5640051" "5926951" "5936843" "6002177").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/28 21:10
S7	268	S4 not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 21:17
S8	1	("4939567").PN.	USPAT	OR	OFF	2004/11/28 21:27
S9	2	(("5644157") or ("6515334")).PN.	USPAT	OR	OFF	2004/11/28 21:27
S10	11	("20010026444" "20020022277" "20020037624" "20030015754" "5529831" "5618761" "5818079" "5821005" "5989635" "6392265" "6649954").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/28 21:45
S11	11	("20010026444" "20020022277" "20020037624" "20030015754" "5529831" "5618761" "5818079" "5821005" "5989635" "6392265" "6649954").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/28 22:03

EAST Search History

S12	10208	((438/353) or (438/359) or (438/400) or (438/421) or (438/422) or (438/424) or (438/437) or (438/453) or (438/597) or (438/598) or (438/619) or (438/637) or (438/638) or (438/642) or (438/643) or (438/652) or (438/653) or (438/667) or (438/668) or (438/672) or (438/675)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/15 18:32
S13	4505	S12 and (via\$1 or (via\$1 near2 hole\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/02 16:13
S14	2463	S13 and ((insulat\$3 or dielectric or barrier) near4 (via\$1 or (via\$1 near2 hole\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 18:38
S15	2406	S14 and (wafer\$1 or substrate\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 18:41
S16	1942	S15 and ((die or (die near2 assembl\$3)) or (ic or (integrated near2 circuit\$1)) or chip\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 18:43
S17	623	S16 and (stack\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 18:44
S18	315	S17 and (conductor\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 18:59
S19	28914	(via\$1 near3 structure\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 19:50

EAST Search History

S20	5411	(via\$1 near3 structure\$1) same (insulat\$3 or dielectric or barrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 20:16
S21	387	(via\$1 near3 structure\$1) same (insulat\$3 or dielectric or barrier) same wafer\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 19:51
S22	381	S21 not S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 19:51
S23	9	("4688069" "4733287" "4939567" "4949151" "5644157" "5760452" "6051868" "6472723" "6515334"). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/15 20:00
S24	0	("6750516").URPN.	USPAT	OR	OFF	2005/01/15 20:02
S25	29	("4093503" "4108715" "4124933" "4271422" "4343675" "4379001" "4438556" "4450041" "4514251" "4571817" "4601778" "4952446" "5092957" "5112771" "5136344" "5236547" "5242863" "5244826" "5336912" "5358908" "5431777" "5484740" "5488011" "5580811" "5599736" "5600174" "5661064" "5817580" "6261964").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/15 20:05
S26	3	("6599840").URPN.	USPAT	OR	OFF	2005/01/15 20:07
S27	929	(via adj structure\$1) same (insulat\$3 or dielectric or barrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 20:17
S28	434	S27 and conductor\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 20:17

EAST Search History

S29	234	S28 and wafer\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 20:17
S30	199	S29 not S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/15 20:17
S31	3	("3903427" "4791248" "4981525").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/15 20:30
S32	23	("5425816").URPN.	USPAT	OR	OFF	2005/01/15 20:30
S33	245	(438/620).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/07 21:37
S34	271	(438/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/26 15:24
S35	0	("002not1").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/23 19:47
S36	260	S34 not S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/23 19:47
S37	1	("6743708").PN.	USPAT	OR	OFF	2005/01/23 20:26
S38	2	("6297145" "6559045").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/23 20:24
S39	0	("6743708").URPN.	USPAT	OR	OFF	2005/01/23 20:25
S40	1	("6498090").PN.	USPAT	OR	OFF	2005/01/23 20:26
S41	2	("6191023" "6198170").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/23 20:26

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S42	1	("6498090").URPN.	USPAT	OR	OFF	2005/01/23 20:32
S43	16	"5529950"	USPAT	OR	OFF	2005/01/23 20:33
S44	1	("5529950").PN.	USPAT	OR	OFF	2005/01/23 20:33
S45	12	("4437109" "4667220" "4893174" "4939568" "5153814" "5244817" "5262021" "5306647" "5360759" "5401672" "5403752" "5426072").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/23 22:19
S46	15	("5529950").URPN.	USPAT	OR	OFF	2005/01/23 20:37
S47	66963	("438").CLAS.	USPAT	OR	OFF	2005/01/23 22:23
S48	1	("4939567").PN.	USPAT	OR	OFF	2005/01/23 22:27
S49	1	("5644157").PN.	USPAT	OR	OFF	2005/01/23 22:29
S50	1	("6515334").PN.	USPAT	OR	OFF	2005/01/23 22:29
S51	10447	((438/353) or (438/359) or (438/400) or (438/421) or (438/422) or (438/424) or (438/437) or (438/453) or (438/597) or (438/598) or (438/619) or (438/637) or (438/638) or (438/642) or (438/643) or (438/652) or (438/653) or (438/667) or (438/668) or (438/672) or (438/675)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/04 16:03
S52	4575	S51 and (wafer\$1 and substrate\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 16:04
S53	494880	"3" and ((dielectric or insulat\$3) near2 (layer\$1 or film\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/02 15:59
S54	3848	S52 and ((dielectric or insulat\$3) near2 (layer\$1 or film\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 16:04
S55	942	S52 and ((first and second) near ((dielectric or insulat\$3) near2 (layer\$1 or film\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/02 16:09

EAST Search History

S56	629	S55 and (via\$1 or (via\$1 near2 hole\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 16:05
S57	279	(438/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/03 18:36
S58	8	("5447871").URPN.	USPAT	OR	OFF	2005/04/03 19:56
S59	1	("6838362").PN.	USPAT	OR	OFF	2005/04/03 23:39
S60	10	("3761782" "4978639" "5091331" "5272104" "5352926" "5426072" "5447871" "5753529" "5757081" "6313531").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/03 23:39
S61	0	("6838362").URPN.	USPAT	OR	OFF	2005/04/03 23:41
S62	283	(438/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/07 21:37
S63	283	(438/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/26 20:33
S64	9	S63 and (stack\$3 near wafer\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 20:34
S65	1	("5998292").PN.	USPAT	OR	OFF	2005/10/20 20:58
S66	1	("3769562").PN.	USPAT	OR	OFF	2005/10/20 20:59
S67	1	("3663308").PN.	USPAT	OR	OFF	2005/10/20 21:07
S68	11724	((438/353) or (438/359) or (438/400) or (438/421) or (438/422) or (438/424) or (438/437) or (438/453) or (438/597) or (438/598) or (438/619) or (438/637) or (438/638) or (438/642) or (438/643) or (438/652) or (438/653) or (438/667) or (438/668) or (438/672) or (438/675)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/07 21:23

EAST Search History

S69	5245	S68 and (wafer\$1 and substrate\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:24
S70	4862	S69 and (dielectric or insulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:24
S71	2846	S70 and (via\$1 or (via\$1 near2 hole\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 16:16
S72	1361	(dic\$3 or saw\$3 or cutt\$3 or ablat\$3) with (stack\$2 near10 (wafer\$1 or (integrated adj circuit\$1) or ic\$1 or chip\$1 or substrate\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 14:35
S73	830	S72 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 14:36
S74	225	S73 and (isolat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/07 21:28